

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kousuke Ohtani	09/17/2009
Yasuhito Ijichi	09/17/2009
RECEIVING PARTY DATA	
Name:	Sumitomo Chemical Co., Ltd.
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Postal Code:	104-8260
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12559223
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ASSIGNMENT

WHEREAS, Kousuke Ohtani and Yasuhito Ijichi, hereinafter called the "Assignors", have made the invention described in the United States patent application entitled HIGH PERFORMANCE THERMOPLASTIC ELASTOMER COMPOSITION, with co-inventor Nadeem Bokhari for a full description of which reference is here made to an application for Letters Patent of the United States filed on September 14, 2009, and assigned Application No. 12/559,223:

WHEREAS, Sumitomo Chemical Co., Ltd. (hereinafter "Sumitomo"), a corporation organized and existing under the laws of Japan, having a place of business at 27-1, Shinkawa 2-Chome, Chuo-ku, Tokyo 104-8260, Japan, hereinafter called the "Assignee", desires to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, for valuable consideration that I acknowledge, the Assignors hereby sell and assign to the Assignee, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents therefor in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; together with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignors hereby covenant and agree, for the Assignors and the Assignors' legal representatives, that the Assignors will assist the Assignees in the prosecution of

the patent application identified above; in the making and prosecution of any other patent applications that the Assignee may elect to make covering the invention identified above; in vesting in the Assignee like exclusive title in and to all such other patent applications and patents; and in the prosecution of any interference which may arise involving said invention, or any such patent application or patent; and that the Assignors will execute and deliver to the Assignee any and all additional papers which may be requested by the Assignee to carry out the terms of this Assignment.

The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignors have executed this agreement.

DATED: Sep. 17, 2009

Kousuke Ohtani
Kousuke Ohtani

DATED: September 17th, 2009

Yasuhito Ijichi
Yasuhito Ijichi